



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

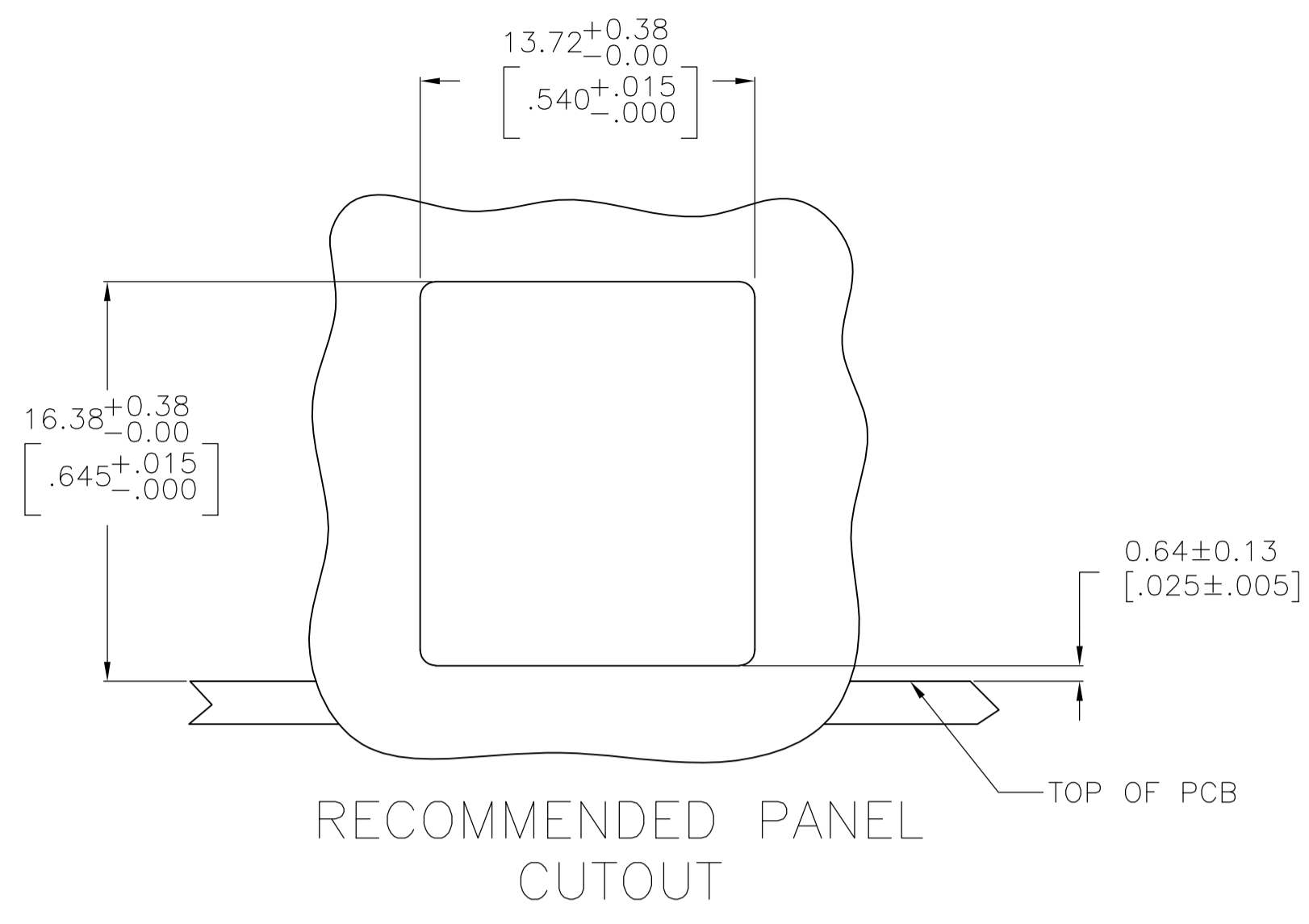
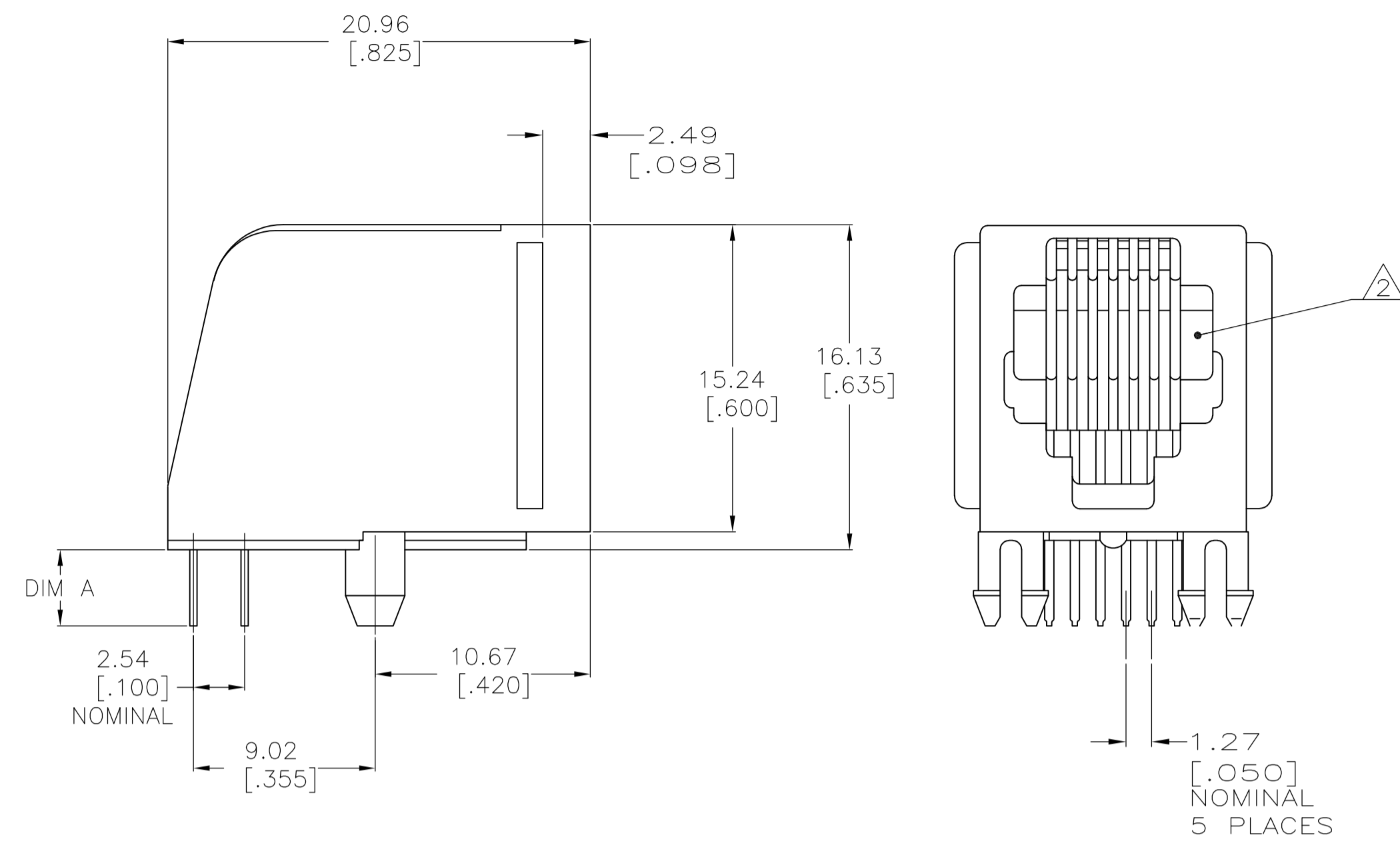
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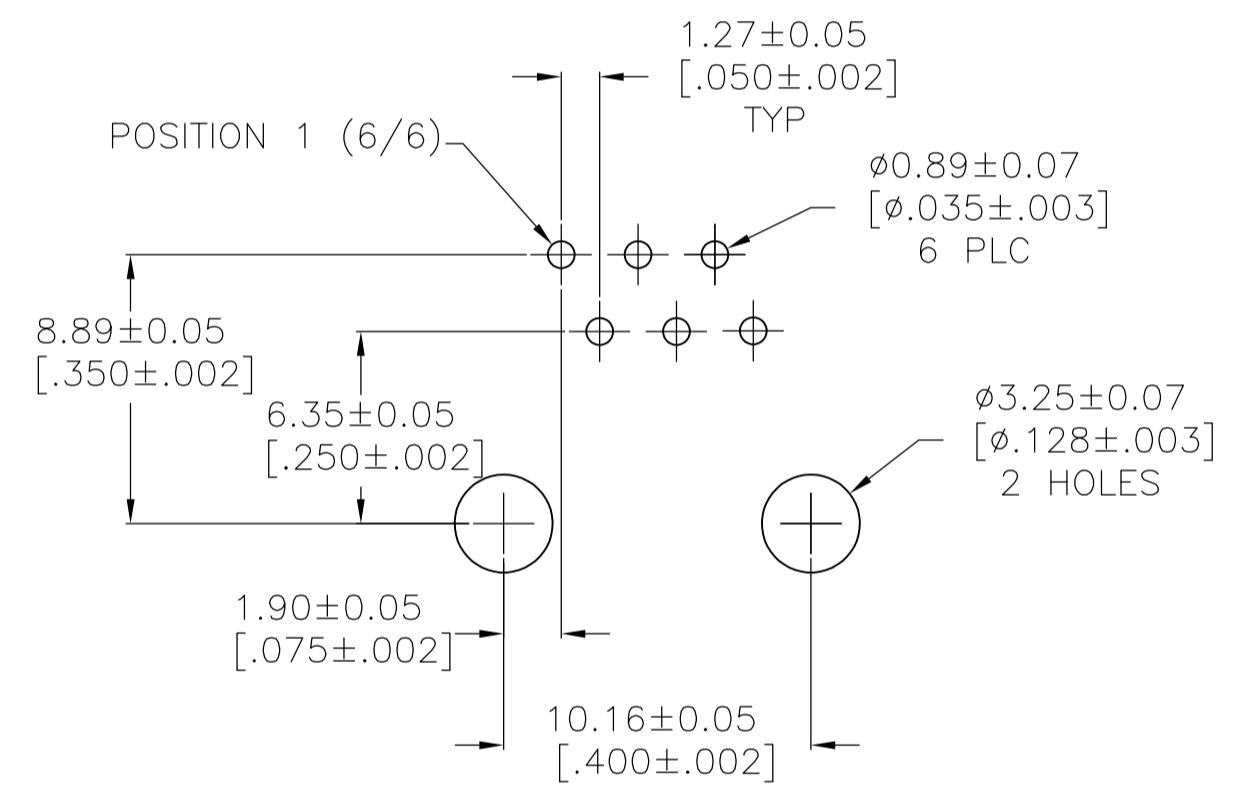
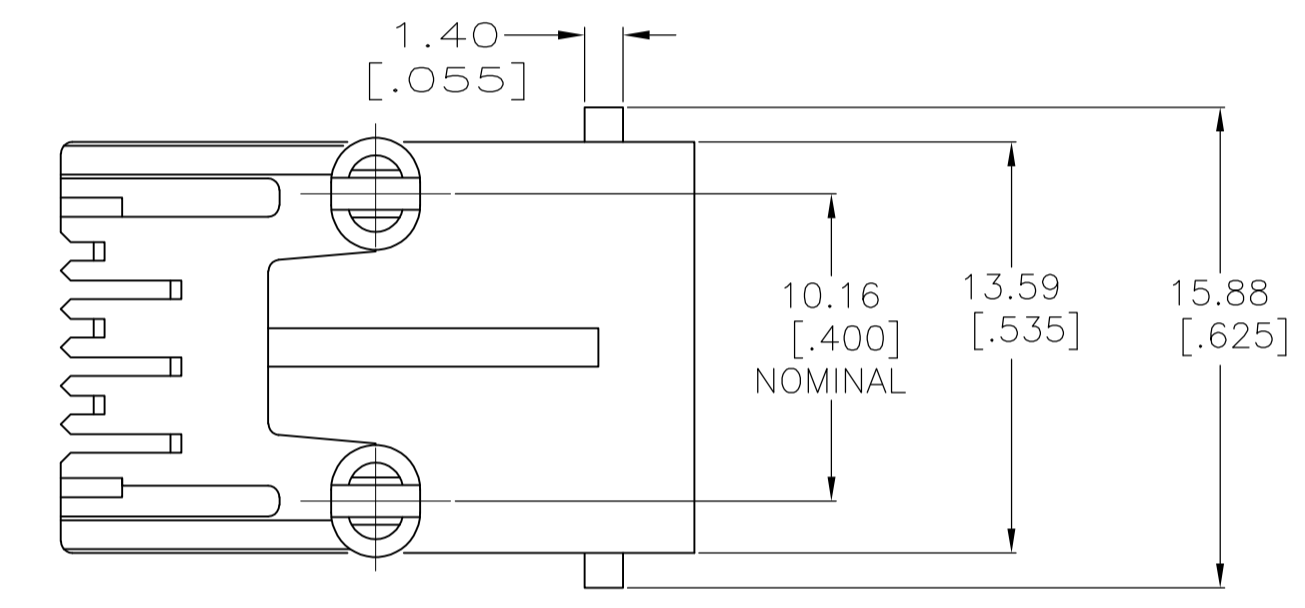
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



LOC		DIST		REVISIONS			
GP	00	REV	DATE	BY	CHK	APPV	
D2	REVISED PER ECO-12-014371		15NOV2012	CJV	PAR		



- MATERIAL:
HOUSING - PBT POLYESTER, COLOR: BLACK
TERMINAL - 0.36[.014] THICK PHOS BRONZE PLATED WITH (SEE TABLE) MIN HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 2.03µm[.000080] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MIN THICK NICKEL UNDERPLATE
- CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.
- 0.15µm[.000006] GOLD PLATED PARTS DO NOT MEET THE MINIMUM GOLD THICKNESS REQUIREMENT OF FCC SPECIFICATION, PART 68. PARTS HAVE NOT BEEN TESTED TO THE DURABILITY REQUIREMENTS OF TE PRODUCT SPEC 108-1163
- TERMINALS FOR 5520250-1 AND -2 LOCATED IN CENTER POSITIONS
- DIMENSIONS ARE MAXIMUM UNLESS OTHERWISE SPECIFIED



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE SHOWN

OBSOLETE	0.15µm[.000006]	3.30-4.32 [.130-.170]	6	2-5520250-3
			4	2-5520250-2
		2.16-2.67 [.085-.105]	4	1-5520250-1
	1.27µm[.000050]	3.30-4.32 [.130-.170]	6	5520250-3
			4	5520250-2
			2	5520250-1
	GOLD THICKNESS	DIM A	TERMINALS REQUIRED	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DIN T. WOOTEN/L.A. MAYER 12MAY2005	CHK J. WESTMAN 12MAY2005	APVD S. FLICKINGER 12MAY2005	NAME
0 PLC ± -	1 PLC ± -	2 PLC ± 0.13[.005]	3 PLC ± -	4 PLC ± -	ANGLES ± -
SEE NOTE 1	SEE NOTE 1	WEIGHT	SCALE 4:1	SHEET 1 OF 1	REV D2

STE TE Connectivity

MODULAR JACK ASSEMBLY, 6 POSITION, SIDE ENTRY, FLANGELESS, WITH PANEL STOPS

108-1163

114-2048

00779C=5520250

CUSTOMER DRAWING